

November 2013

#### FDB38N30U

## N-Channel UniFET<sup>TM</sup> Ultra FRFET<sup>TM</sup> MOSFET 300 V, 38 A, 120 m $\Omega$

#### **Features**

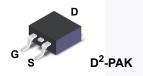
- $R_{DS(on)}$  = 120  $m\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 19 A
- Low Gate Charge (Typ. 56 nC)
- Low C<sub>rss</sub> (Typ. 55 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

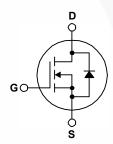
#### **Applications**

- · Uninterruptible Power Supply
- LCD/LED/PDP TV
- · AC-DC Power Supply

#### Description

UniFET<sup>TM</sup> MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. UniFET Ultra FRFET<sup>TM</sup> MOSFET has much superior body diode reverse recovery performance. Its trr is less than 50nsec and the reverse dv/dt immunity is 20V/nsec while normal planar MOSFETs have over 200nsec and 4.5V/nsec respectively. Therefore UniFET Ultra FRFET MOSFET can remove additional component and improve system reliability in certain applications that require performance improvement of the MOSFET's body diode. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





#### **MOSFET Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FDB38N30U	Unit
$V_{DSS}$	Drain to Source Voltage			300	V
$V_{GSS}$	Gate to Source Voltage	Gate to Source Voltage		±30	V
	Drain Current - Continuous (T <sub>C</sub> = 25°C)			38	A
ID	DrainCurrent	- Continuous (T <sub>C</sub> = 100°C	5)	22.8	A
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	152	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		(Note 2)	722	mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	38	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		(Note 1)	31.3	mJ
dv/dt	Peak Diode Recovery dv	/dt	(Note 3)	20	V/ns
D	Power Dissination	$(T_C = 25^{\circ}C)$		313	W
$P_{D}$	Power Dissipation	- Derate Above 25°C		2.5	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C
$T_L$	Maximum Lead Tempera	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			°C

#### **Thermal Characteristics**

Symbol	Parameter	FDB38N30U	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.4	°C/W
$R_{\theta,JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	30/00

#### **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDB38N30U	FDB38N30U	D <sup>2</sup> -PAK	Tape and Reel	330 mm	24 mm	800 units

#### **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$	300	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 μA, Referenced to 25°C	-	0.33	-	V/°C
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 0 V	-	-	25	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 240 \text{ V}, T_C = 125^{\circ}\text{C}$	-	-	250	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19 A	-	0.103	0.120	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 19 \text{ A}$	-	30	-	S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 05.V.V 0.V	-	2510	3340	pF
Coss	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1  MHz		470	625	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	55	85	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 240 V, I <sub>D</sub> = 38 A	-	56	73	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	14	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	24	-	nC

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	33	76	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 150 \text{ V}, I_D = 38 \text{ A},$	-	80	170	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$	-	133	276	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	62	134	ns

#### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Diode Forward Current		_	-	38	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	152	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A,	-	60	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge dI <sub>F</sub> /dt = 100 A/μs		-	0.097	_	μС

#### Notes:

- 1: Repetitive rating: pulse-width limited by maximum junction temperature.
- 2: L = 1 mH,  $I_{AS}$  = 38 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.
- 3:  $I_{SD} \le 38$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_J = 25^{\circ}C$ .
- 4: Essentially Independent of Operating Temperature Typical Characteristics.

#### **Typical Performance Characteristics**

Figure 1. On-Region Characteristics 100 V<sub>GS</sub> = 15.0V 10.0V 8.0V 7.0V 6.5V Ip, Drain Current[A] 6.0V 1. 250µs Pulse Test 2.  $T_C = 25^{\circ}C$ 0.1 0.1 10 1 V<sub>DS</sub>, Drain-Source Voltage[V] 20

Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

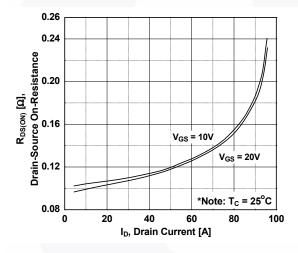


Figure 5. Capacitance Characteristics

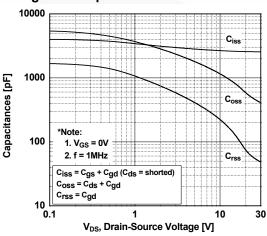


Figure 2. Transfer Characteristics

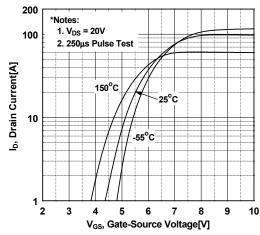


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

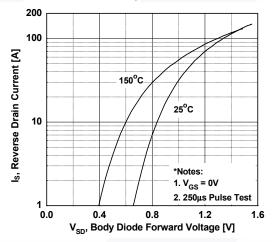
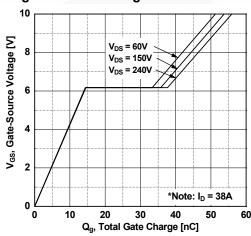


Figure 6. Gate Charge Characteristics



#### **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

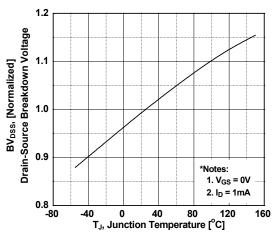


Figure 9. Maximum Drain Current vs. Case Temperature

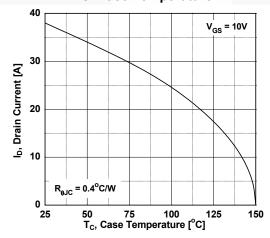


Figure 8. Maximum Safe Operating Area

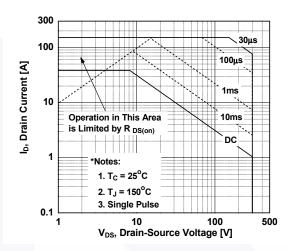


Figure 10. Unclamped Inductive Switching Capability

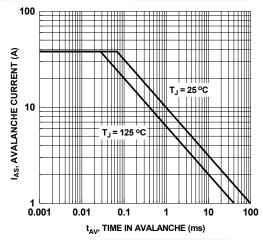
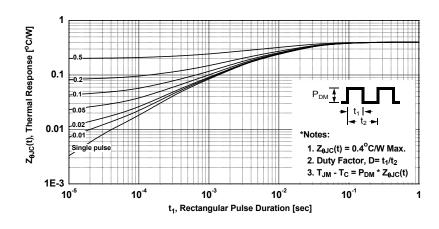


Figure 11. Transient Thermal Response Curve



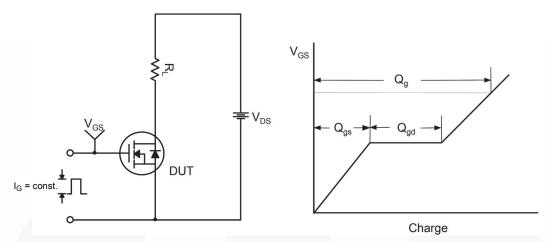


Figure 12. Gate Charge Test Circuit & Waveform

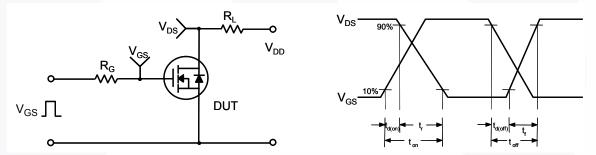


Figure 13. Resistive Switching Test Circuit & Waveforms

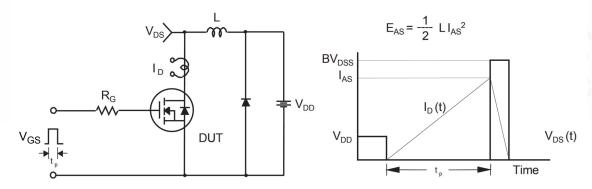


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

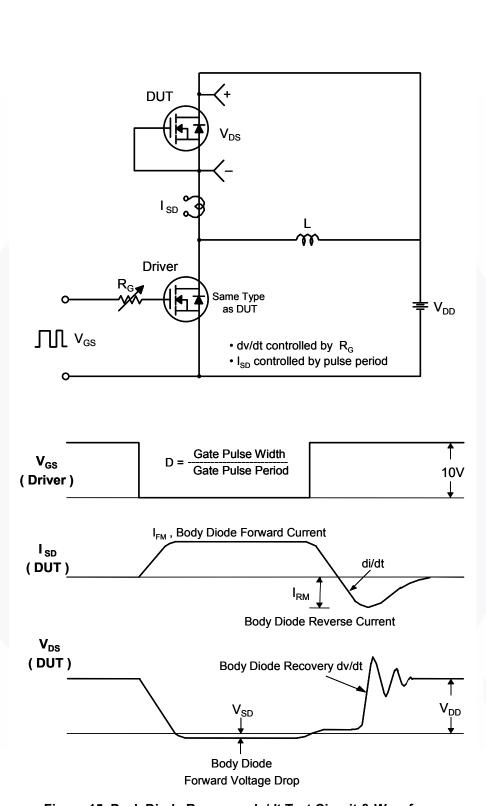


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **Mechanical Dimensions**

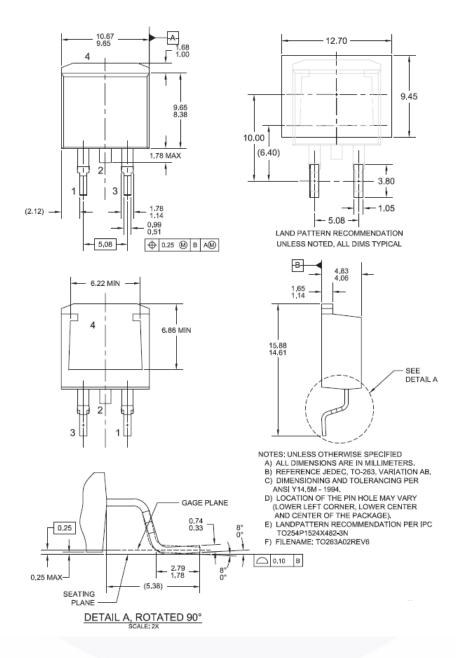


Figure 16. TO263 (D<sup>2</sup>PAK), Molded, 2-Lead, Surface Mount

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